

广东星坤科技股份有限公司  
 文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES
Δ*	日期				ANGLAR $\pm 5^\circ$
Δx					$L \leq 4$ $\pm 0.2$
Δx					$4 < L \leq 16$ $\pm 0.3$
					$16 < L \leq 63$ $\pm 0.4$
					$L > 63$ $\pm 0.5$



DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	PART NO.: X1304WWS-52X-LPV10
CHKD	UNIT: mm/in	DWG NO.:
APPD	SIZE: A4	X-X1304WWS-52X-LPV10
XKB INDUSTRIAL PRECISION CO., LIMITED		WEIGHT
		SHEET
		REVISION
		1/1
		A0

NOTES 注释:

1. MATERIAL 材料:

HOUSING 外壳: THERMOPLASTIC, HIGH TEMP.,  
UL94V-0; BLACK COLOR

CONTACTS 触点: COPPER ALLOY.

PEGS 螺钉: COPPER ALLOY.

2. FINISH 饰面:

CONTACT 触点: SELECTIVE GOLD PLATING ON CONTACT AREA.  
100μ" MIN. MATTE TIN PLATING ON SOLDER TAILS,  
50μ" MIN. NICKEL UNDERPLATING OVERALL.

PEGS 螺钉: 120u" MIN. MATTE-TIN OVER 50u" MIN. NICKEL.

X1304 W V S - 52 X - LP V10

① ② ③ ④ ⑤ ⑥ ⑦ ⑧

① Series Number

② Terminal form: W-Wafer

③ Welding Board Angle : V-Stright Angle 180°

④ Welding Way: S-SMT

⑤ No. of Pins: 52 PIN

⑥ HEIGHT: A 4.0mm; B 5.2mm; C 5.6mm; D 6.8mm;  
E 7.0mm; F 8.0mm; G 9.0mm; H 9.9mm

⑦ Plastic material: LP-LCP UL94V-0

⑧ Contact Plating: V01-Gold Flash  
V10-Gold 10 u"  
V30-Gold 30 u"

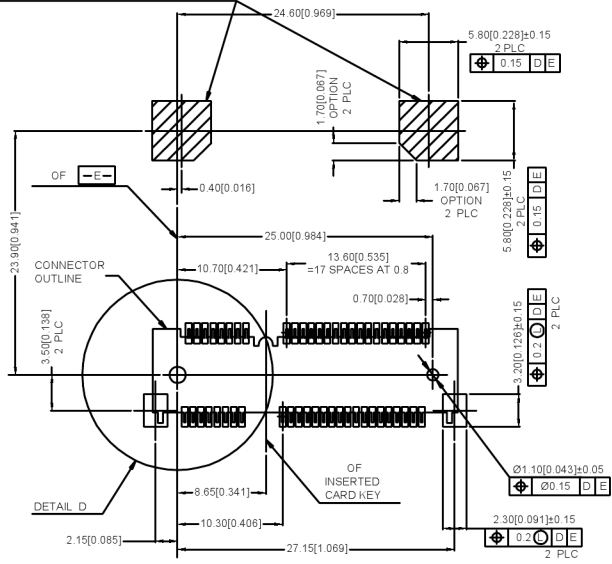
广东星坤科技股份有限公司

Δ	日期
Δ	
Δ	
MARK	文件工程章

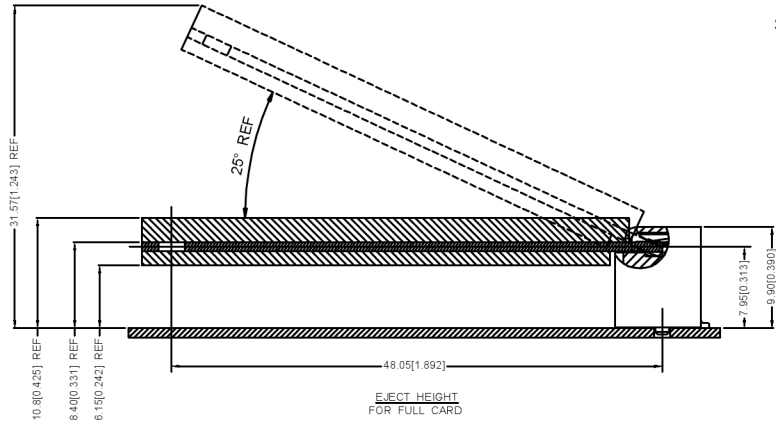
					ANGLAR	±5°
					L ≤ 4	±0.2
					4 < L ≤ 16	±0.3
					16 < L ≤ 63	±0.4
					L > 63	±0.5
REVISIONS					UNSPECIFIED TOLERANCES	

XKLB	DSND	SCALE: N/A	MODEL TYPE:
	DWN	VIEW:	PART NO.: X1304WVS-52X-LPV10
	CHKD	UNIT: mm/in	DWG NO.: X-X1304WVS-52X-LPV10
	APPD	SIZE: A4	WEIGHT
XKB INDUSTRIAL PRECISION CO., LIMITED			SHEET 1/1
			REVISION A0

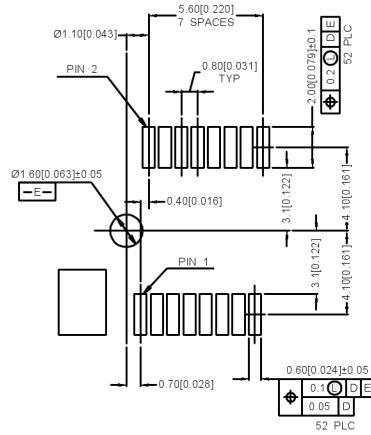
COMPONENT KEEP OUT AREA FOR CARD HOLD DOWN SOLUTION



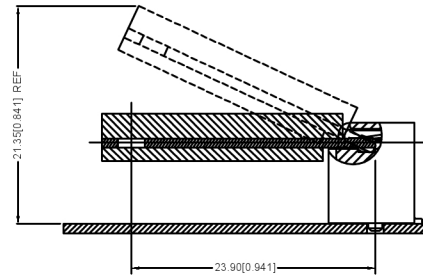
—D— IS THE TOP SURFACE OF PCB.  
RECOMMENDED P.C. BOARD PATTERN LAYOUT  
FOR HALF CARD CONNECTOR  
(TOP VIEW)



EJECT HEIGHT  
FOR FULL CARD

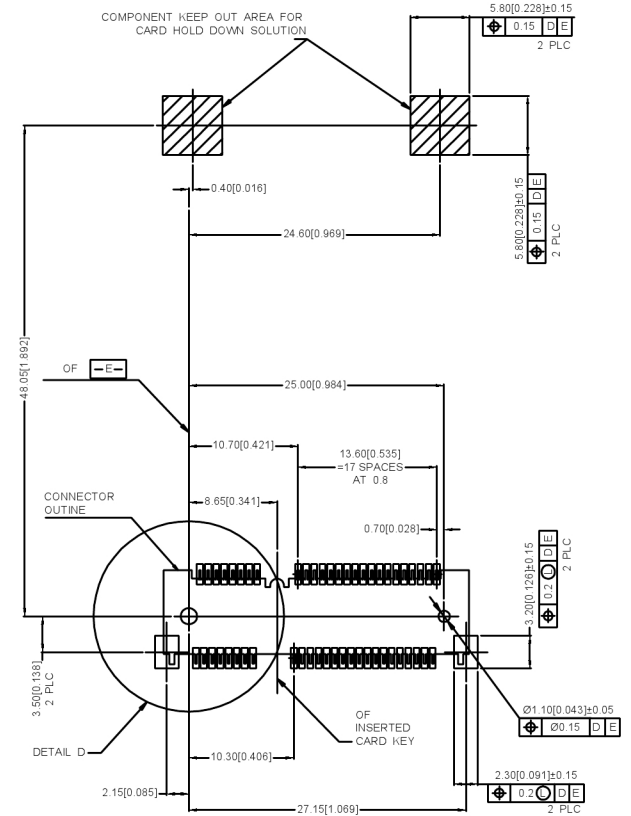


DETAIL D  
SCALE 2:1



EJECT HEIGHT  
FOR HALF CARD

COMPONENT KEEP OUT AREA FOR CARD HOLD DOWN SOLUTION



—D— IS THE TOP SURFACE OF PCB.  
RECOMMENDED P.C. BOARD PATTERN LAYOUT  
FOR HALF CARD CONNECTOR  
(TOP VIEW)

广东星坤科技股份有限公司

Δ建	日期
Δ改	日期
ΔX	日期
MARK	DESCRIPTION

DESCRIPTION

REVISIONS

DATE

REVISED

APPROVED

ANGLAR	±5°
L ≤ 4	±0.2
4 < L ≤ 16	±0.3
16 < L ≤ 63	±0.4
L > 63	±0.5

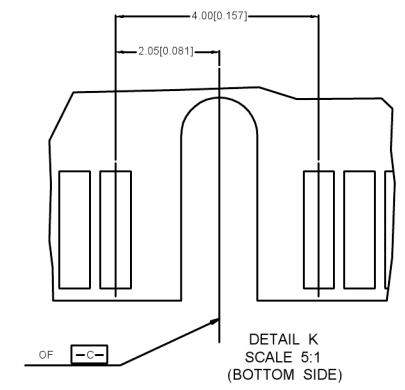
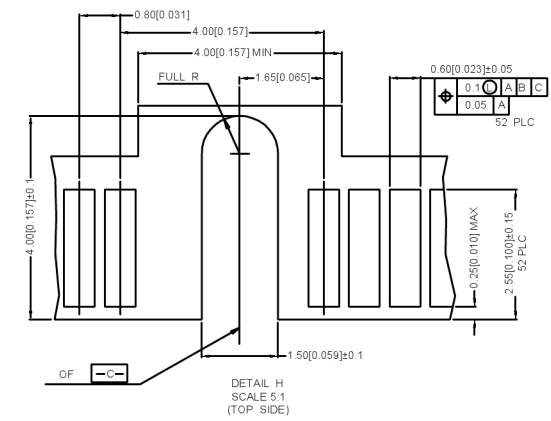
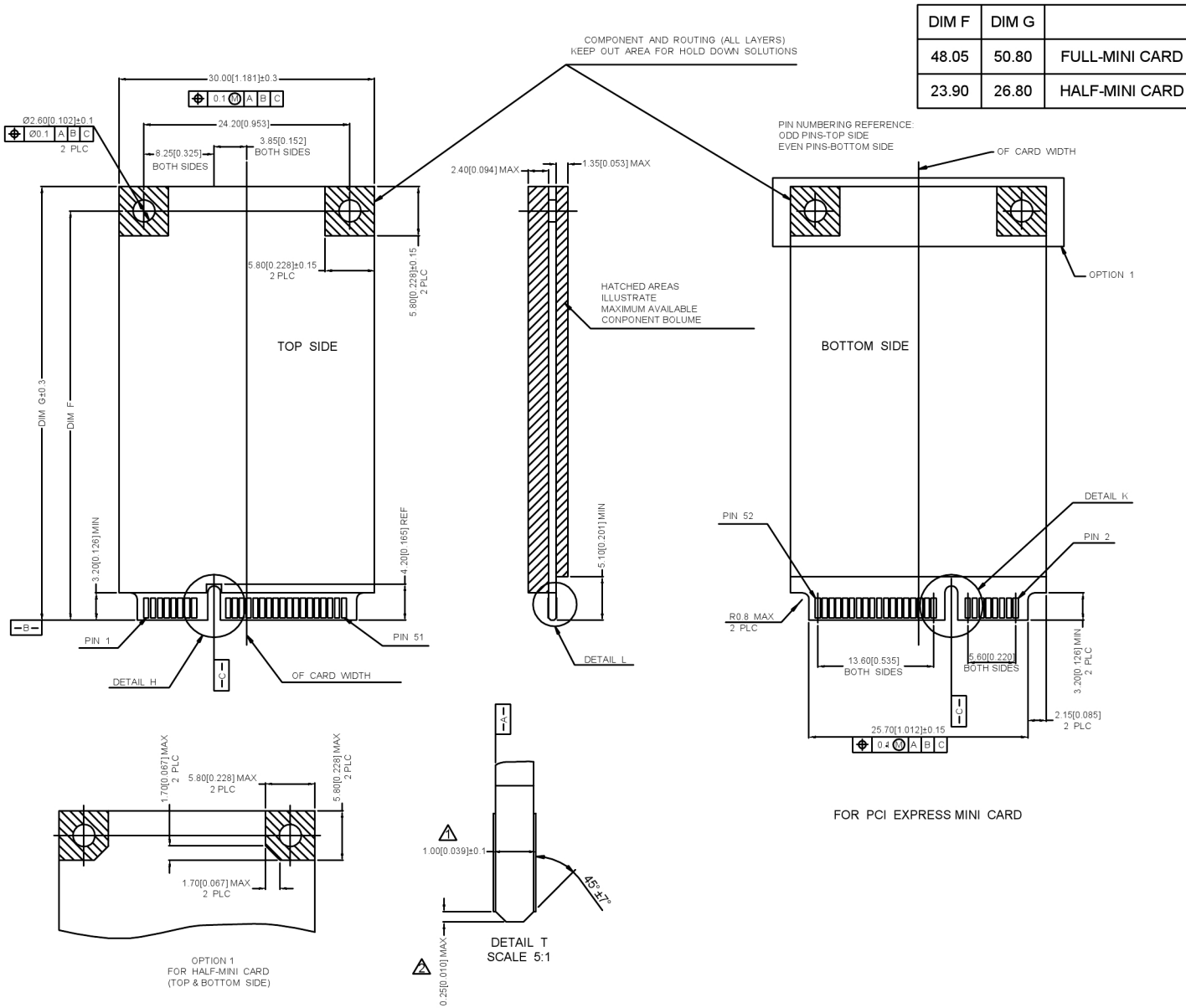
UNSPECIFIED TOLERANCES

XKLB

DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	PART NO.: X1304WVS-52X-LPV10
CHKD	UNIT: mm/in	DWG NO.:
APPD	SIZE: A4	X-X1304WVS-52X-LPV10

XKB INDUSTRIAL PRECISION CO., LIMITED

WEIGHT	SHEET	REVISION
	1/1	A0



NOTES 注释:

- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.  
卡片厚度适用于所有接线片，包括电镀和/或金属化。
- △ EDGE BEVEL MUST BE PRESENT AND FREE OF CUTTING CONTACT MATERIALS SURF BURRS FROM AND PCB  
边缘斜面必须均匀且无切割接触材料毛刺和PCB

广东星坤科技股份有限公司

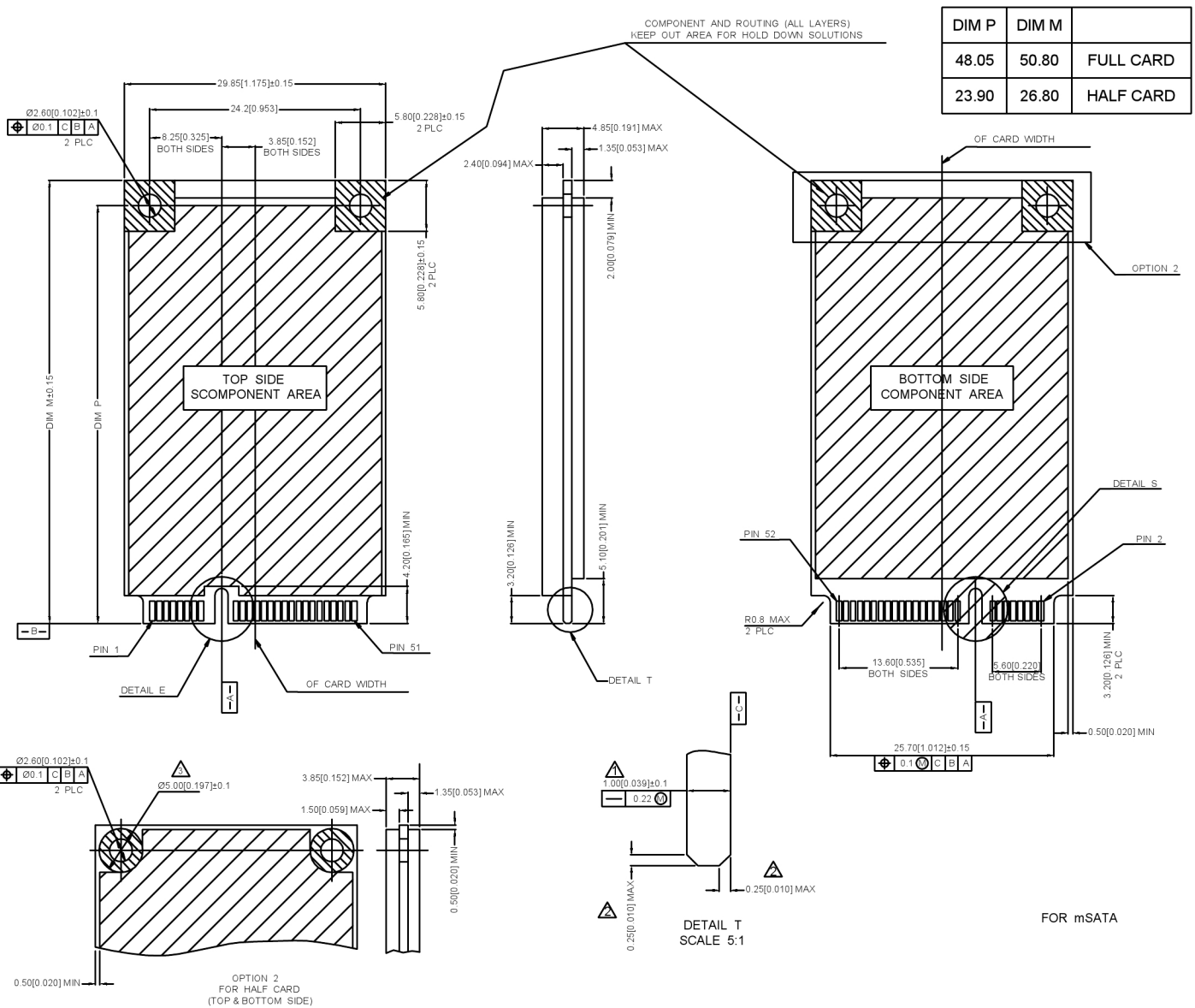
DATE	日期
DESCRIPTION	文件工程章
REVISIONS	

www.helloxkb.com www.helloxkb.com www.xk-dg.cn

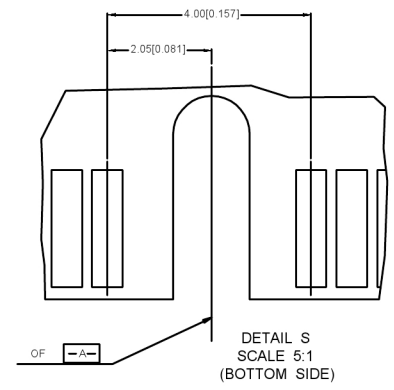
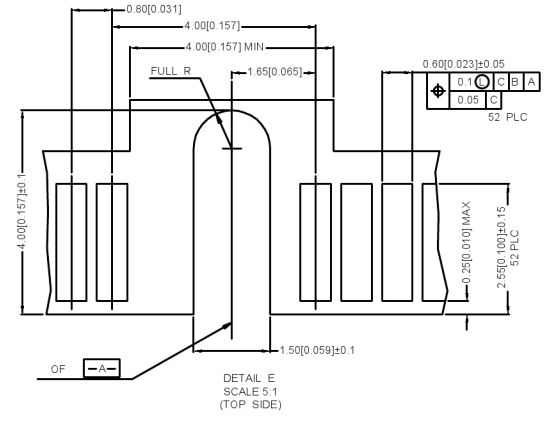
ANGLAR	±5°
L ≤ 4	±0.2
4 < L ≤ 16	±0.3
16 < L ≤ 63	±0.4
L > 63	±0.5
UNSPECIFIED TOLERANCES	



DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	PART NO.: X1304WWS-52X-LPV10
CHKD	UNIT: mm/in	DWG NO.:
APPD	SIZE: A4	X-X1304WWS-52X-LPV10
XKB INDUSTRIAL PRECISION CO., LIMITED		WEIGHT SHEET REVISION 1/1 A0



DIM P	DIM M	
48.05	50.80	FULL CARD
23.90	26.80	HALF CARD



- NOTES 注释:
- △ CARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR METALLIZATION.  
卡片厚度适用于所有接线片，包括电镀和/或金属化。
  - △ EDGE BEVEL MUST BE IPRESENT AND FREE OF CUTTING CONTACT MATERIALS BURRS FROM AND PCB  
边缘斜面必须均匀且无切割接触材料毛刺和PCB
  - △ COMPONENT AND ROUTING (TOP/BOTTOM LAYER) KEEP OUT AREA FOR HOLD DOWN SOLUTIONS.  
元件和布线(顶层/底层)为压紧解决方案留出区域

广东星坤科技股份有限公司

姓名: \_\_\_\_\_ 日期: \_\_\_\_\_  
 数量: \_\_\_\_\_  
 文件工程章

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES

ANGLAR	±5°	XKLB
L ≤ 4	±0.2	
4 < L ≤ 16	±0.3	
16 < L ≤ 63	±0.4	
L > 63	±0.5	
UNSPECIFIED TOLERANCES		XKB INDUSTRIAL PRECISION CO., LIMITED

DSND	SCALE: N/A	MODEL TYPE:
DWN	VIEW:	PART NO.: X1304WVS-52X-LPV10
CHKD	UNIT: mm/in	DWG NO.: X-X1304WVS-52X-LPV10
APPD	SIZE: A4	WEIGHT SHEET REVISION